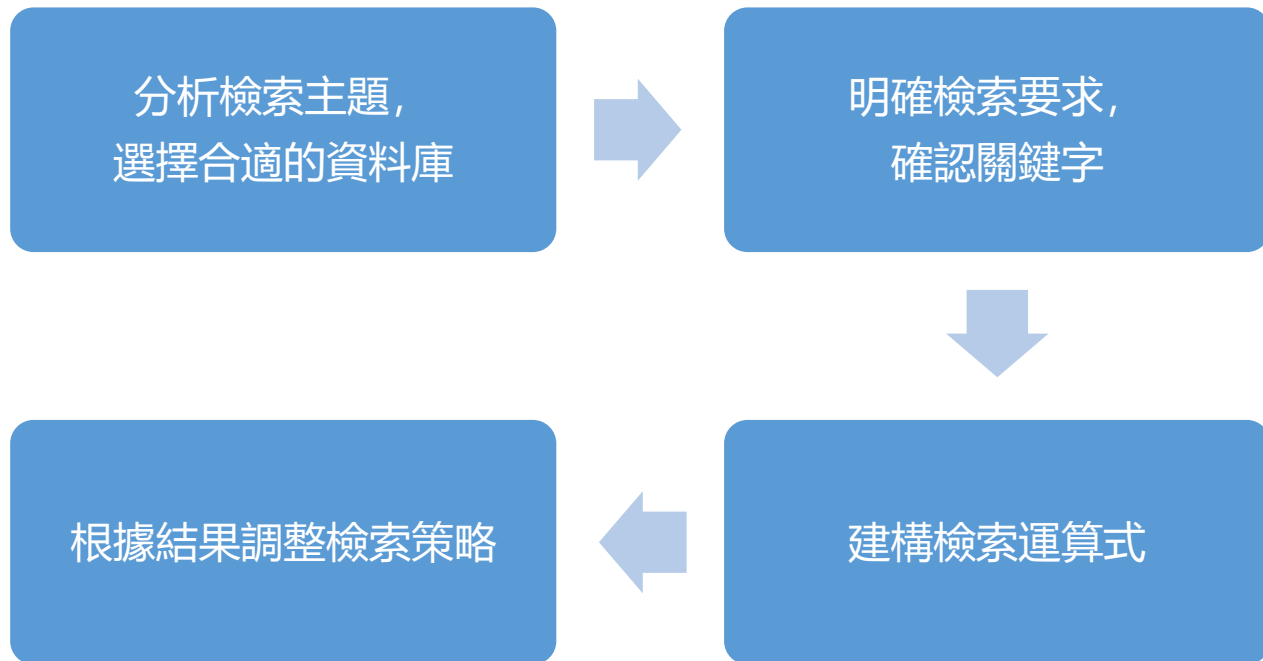




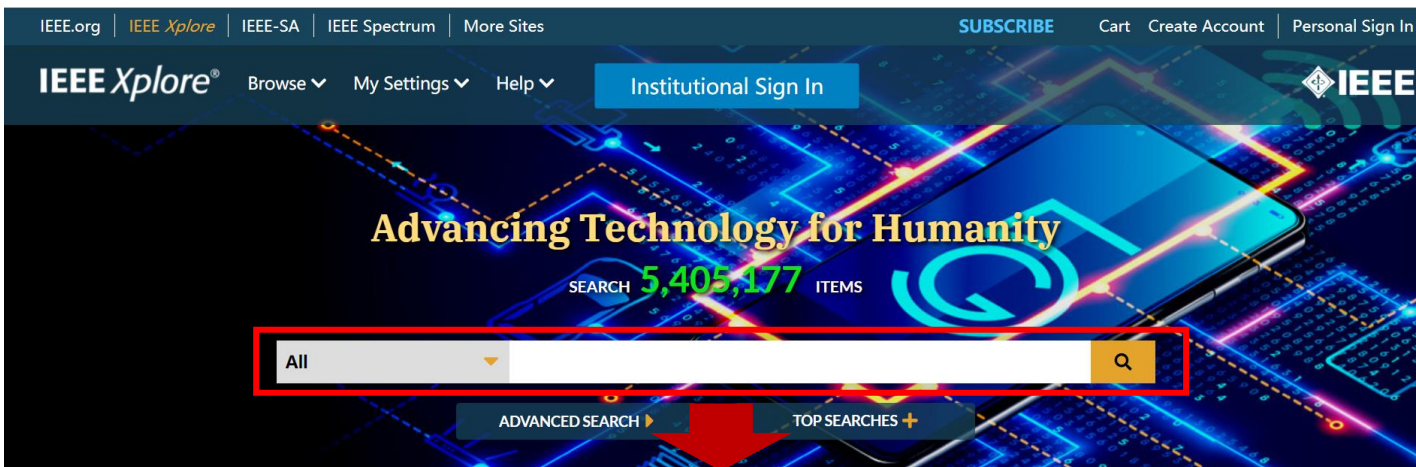
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往期回顧——如何全面準確地檢索文獻資訊




往期回顾——文獻檢索：檢索規則簡介



一框式檢索(Global Search)

1. 預設檢索內容： metadata only
2. 檢索詞之間的默認關係： AND ie. smart grid= smart AND grid
3. 支援命令檢索： ie. "Abstract":ofdm AND "Publication Title":communications
4. 自動獲取詞根： pluralized nouns, verb tenses, and British/American spelling variations
5. 精確檢索使用雙引號： 片語、固定搭配 ie. "java programming"
6. 模糊檢索使用*和?
7. 檢索詞不區分大小寫， 檢索運算全部大寫

往期回顾——檢索結果頁面：瞭解技術整體研發情況


Search within results  Per Page: 25 Export Set Search Alerts Search History

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Mosfet Models for Spice Simulation, Including BSIM3v3 and BSIM4



Author	Affiliation	Publication Title	Publication Topics
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<input type="checkbox"/> Chenming Hu (370)	<input type="checkbox"/> IMEC, Leuven, Belgium (272)	<input type="checkbox"/> IEEE Transactions on Electron Devices (4,972)	<input type="checkbox"/> MOSFET (26,397)
<input type="checkbox"/> G. Ghibaudo (215)	<input type="checkbox"/> Dept. of Electr. Eng. & Comput. Sci., California Univ., Berkeley, CA, USA (260)	<input type="checkbox"/> IEEE Electron Device Letters (2,953)	<input type="checkbox"/> semiconductor device models (8,974)
<input type="checkbox"/> S. Cristoloveanu (206)	<input type="checkbox"/> Dept. of Electron. Eng., Nat. Chiao Tung Univ., Hsinchu, Taiwan (160)	<input type="checkbox"/> IEEE Transactions on Nuclear Science (1,053)	<input type="checkbox"/> CMOS integrated circuits (7,093)
<input type="checkbox"/> G. Groeseneken (203)	<input type="checkbox"/> imec, Leuven, Belgium (134)	<input type="checkbox"/> IEEE Transactions on Power Electronics (931)	<input type="checkbox"/> power MOSFET (5,687)
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<input type="checkbox"/> Yee-Chia Yeo (181)	<input type="checkbox"/> STMicroelectronics, Crolles, France (120)	<input type="checkbox"/> IEEE Transactions on Device and Materials Reliability (330)	<input type="checkbox"/> silicon (4,785)
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Salvador Pinillos Gimenez
Year: 2016 | Book | Publisher: Morgan & Claypool

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往期回顾——文章細節頁面

Hybrid MOSFET/driver for ultra-fast switching

T. Tang; C. Burkhart

IEEE Transactions on Dielectrics and Electrical Insulation

Year: 2009 | Volume: 16, Issue: 4 | Journal Article | Publisher: IEEE

Cited by: Papers (8)

▶ Abstract HTML  

Hybrid MOSFET/driver for ultra-fast switching

Publisher: IEEE

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T. Tang; C. Burkhart All Authors

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Document Sections

I. Introduction

II. Design

III. Results

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Abstract:

The ultra-fast switching of power MOSFETs, in about 1 ns, is very challenging due to the parasitic inductance that is intrinsic to commercial packages used for power MOSFET drivers. Parasitic gate and source inductance not only limit the voltage rise time of the internal gate structure but can also cause the gate voltage to oscillate. This paper describes a hybrid approach that substantially reduces the parasitic inductance between the driver and MOSFET gate, as well as between the MOSFET source and its external connection. A flip-chip assembly is used to directly attach a die-form power MOSFET and driver on a PCB. The parasitic inductances are significantly reduced by eliminating bond wires and minimizing lead length. The experimental results demonstrate ultra-fast switching of the power MOSFET with excellent control of the gate-source voltage.

Published in: IEEE Transactions on Dielectrics and Electrical Insulation (Volume: 16, Issue: 4, August 2009)

Page(s): 967 - 970

INSPEC Accession Number: 10847239

9.5211841

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Coreless printed circuit board (PCB) transformers for power MOSFET/IGBT gate drive circuits
IEEE Transactions on Power Electronics
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HAOYU WANG; YONG LIU; ZIFENG HAN; JIANZHANG WU
2020 International Conference on Artificial Intelligence and Education (ICAIE)
Year: 2020 | Conference Paper | Publisher: IEEE

[▶ Abstract](#) [HTML](#)

Publication Title



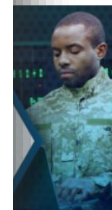
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- IEEE Access (18,295)
- IEEE Transactions on Pattern Analysis and Machine Intelligence (2,308)
- IEEE Transactions on Image Processing (2,188)
- 2011 2nd International Conference on Artificial Intelligence, Management Science and Electronic Commerce (AIMSEC) (1,874)
- IEEE Transactions on Neural Networks (1,626)
- IEEE Transactions on Neural Networks and Learning Systems (1,528)
- IEEE Transactions on Cybernetics (1,058)
- IEEE Transactions on Systems, Man, and Cybernetics, Part B (Cybernetics) (954)
- IEEE Transactions on Knowledge and Data Engineering (928)
- 2020 IEEE/CVF Conference on Computer Vision and Pattern Recognition (CVPR) (926)
- 2020 25th International Conference on Pattern Recognition (ICPR) (921)

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- ▶ **3 of the top 5** journals in **Computer Science, Information Systems**
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- ▶ **3 of the top 5** journals in **Computer Science, Cybernetics**
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8. **Proceedings of the IEEE**
9. **IEEE Transactions on Image Processing**
10. **IEEE Network**
11. **IEEE Transactions on Neural Networks and Learning Systems**
12. **IEEE Vehicular Technology Magazine**
13. **IEEE Transactions on Medical Imaging**
14. **IEEE Communications Magazine**
15. **IEEE Internet of Things Journal**
16. **IEEE Journal on Selected Areas in Communications**
17. **IEEE Transactions on Smart Grid**
18. **IEEE Transactions on Industrial Electronics**
19. **IEEE Transactions on Sustainable Energy**
21. **IEEE Transactions on Information Forensics and Security**
22. **IEEE Transactions on Wireless Communications**
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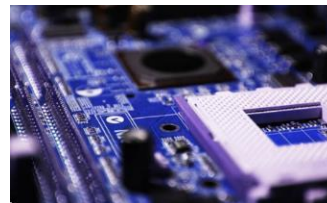
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Coming in 2022: IEEE Transactions on **Signal and Power Integrity**

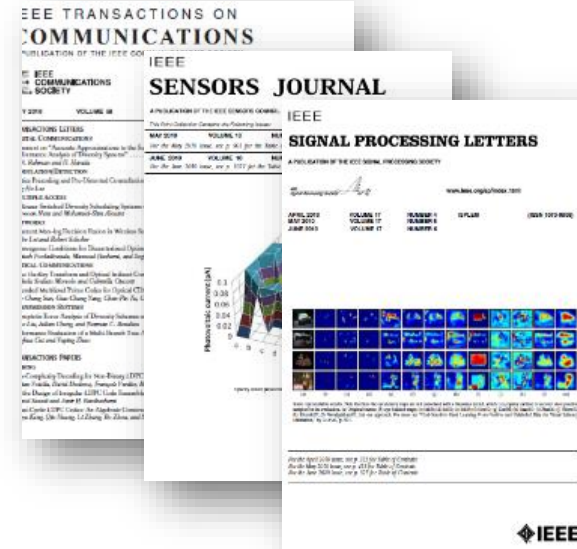
Coming in 2022: IEEE Journal on **Flexible Electronics**



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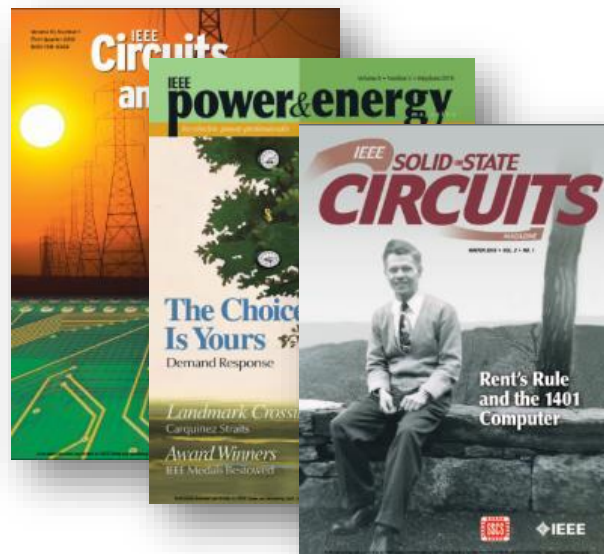
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Application Note	NO	NO	YES
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- ▶ **Research Article:** Papers in the journals use the IEEE standard format and must include a Title, Abstract, Introduction, Technical Content, Conclusions, and References. The transactions also include the author biographies.
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進一步瞭解期刊

- ▶ 一旦確定了4-5本目標期刊，下一步是研究 “Aims and Scope” 以瞭解到底該刊傾向於何種類型的文章
 - 主編
 - 編委成員

- ▶ 閱讀部分期刊收錄的文章，判斷該期刊的讀者群是否吻合

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Aims & Scope

IEEE Internet of Things (IoT) Journal publishes articles on the latest advances, as well as articles, on the various aspects of IoT. Topics include IoT system architecture, IoT enabling technologies, IoT communication and networking protocols such as network coding and applications. Examples are IoT demands, impacts, and implications on sensor data management, and future Internet design for various IoT use cases, such as smart environments, smart homes, etc. The fields of interest include: IoT architecture such as data-centric, service-oriented IoT architecture; IoT enabling technologies and systems such as sensor technologies, big sensor data management, and future Internet design services, applications, and test-beds such as IoT service middleware, IoT application interface (API), IoT application design, and IoT trials/experiments; IoT standardization technology development in different standard development organizations (SDO) such as IEEE, IETF, ITU, 3GPP, etc.

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舉例: IEEE Internet of Things Journal

The image shows a screenshot of the IEEE Internet of Things Journal website. The page features a navigation menu on the left with links for 'Home' and 'For Authors'. The main content area includes sections for 'Call for Papers', 'Manuscript Submission', 'Mandatory Page Charges', 'Manuscript Formats', and 'Multiple Submissions and Prior Publications'. Several overlapping callout boxes are present, highlighting specific text. One box highlights the word 'eight' in the 'Manuscript Submission' section. Another box highlights the text 'The IEEE IoT Journal cannot tolerate unfortunate situations when authors submit the same, or nearly identical, manuscript to more than one place (journals or conferences) or resubmit their prior publications without significant extension. In such cases: a) the manuscript in question will be immediately rejected; b) other manuscripts of the same authors/co-authors currently under review will be returned; c) the authors/co-authors will be prohibited from new submissions to the IEEE IoT Journal for at least one calendar year.' in the 'Multiple Submissions and Prior Publications' section. A third box highlights the text 'published standards; see IEEE Information for Author Digital Too Box at: http://www.ieee.org/publications_standards/publications/authors/authors_journals.html. IEEE IoT Journal requires that derivations which are easily found in the literature merely be cited.' in the same section. A vertical sidebar on the left contains a 'No. of Articles Published' section with a yellow box showing '9.' and a red box showing 'Sub'.

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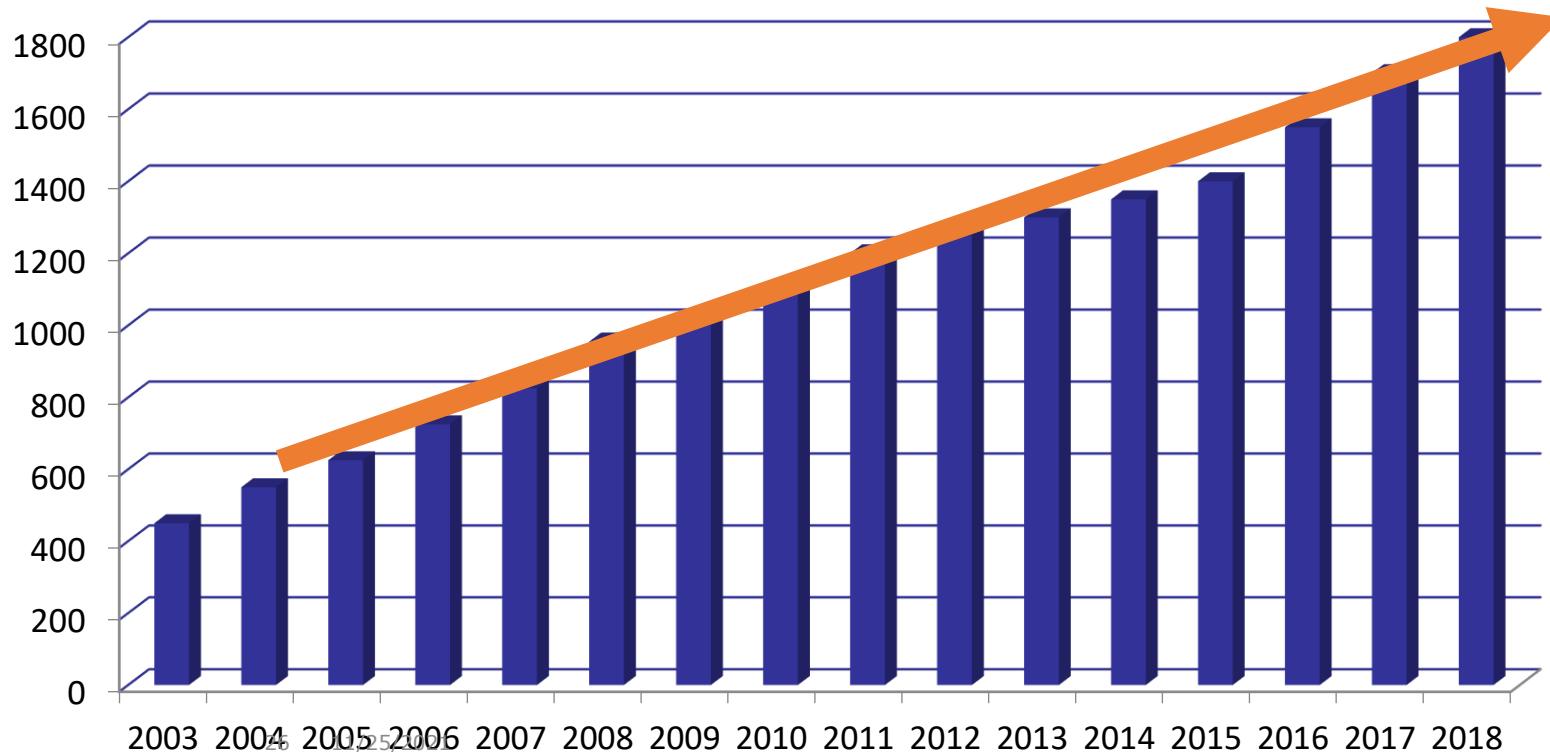
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2022 International Conference on Artificial Intelligence in Information and Communication (ICAIIIC) Location: GU, USA	USA		21-24 Feb 2022
2022 Second International Conference on Artificial Intelligence and Smart Energy (ICAIS) Location: JCT College of Engineering and Technology, Pichanur Road, Off NH 47, Pichanur, Coimbatore, India	India	17 Oct 2021	23-25 Feb 2022

<http://publication-recommender.ieee.org/home>



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15 - 17 September 2021 | Penghu, Taiwan

Sponsors: IEEE Consumer Technology Society

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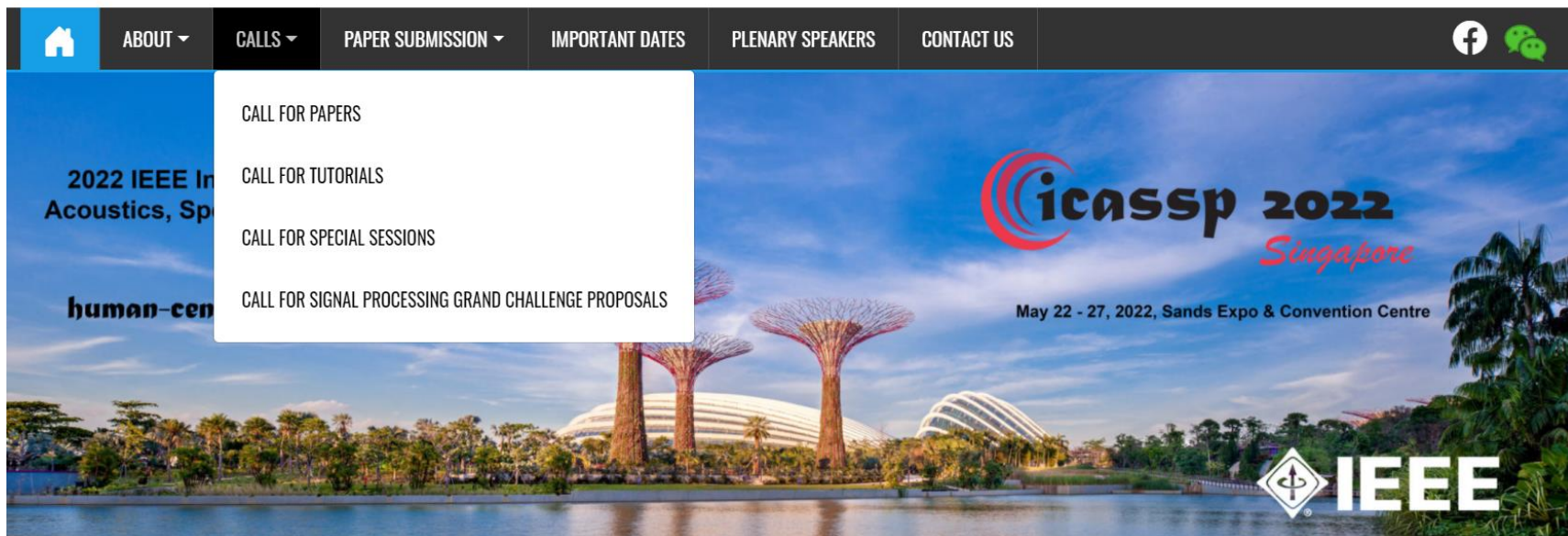
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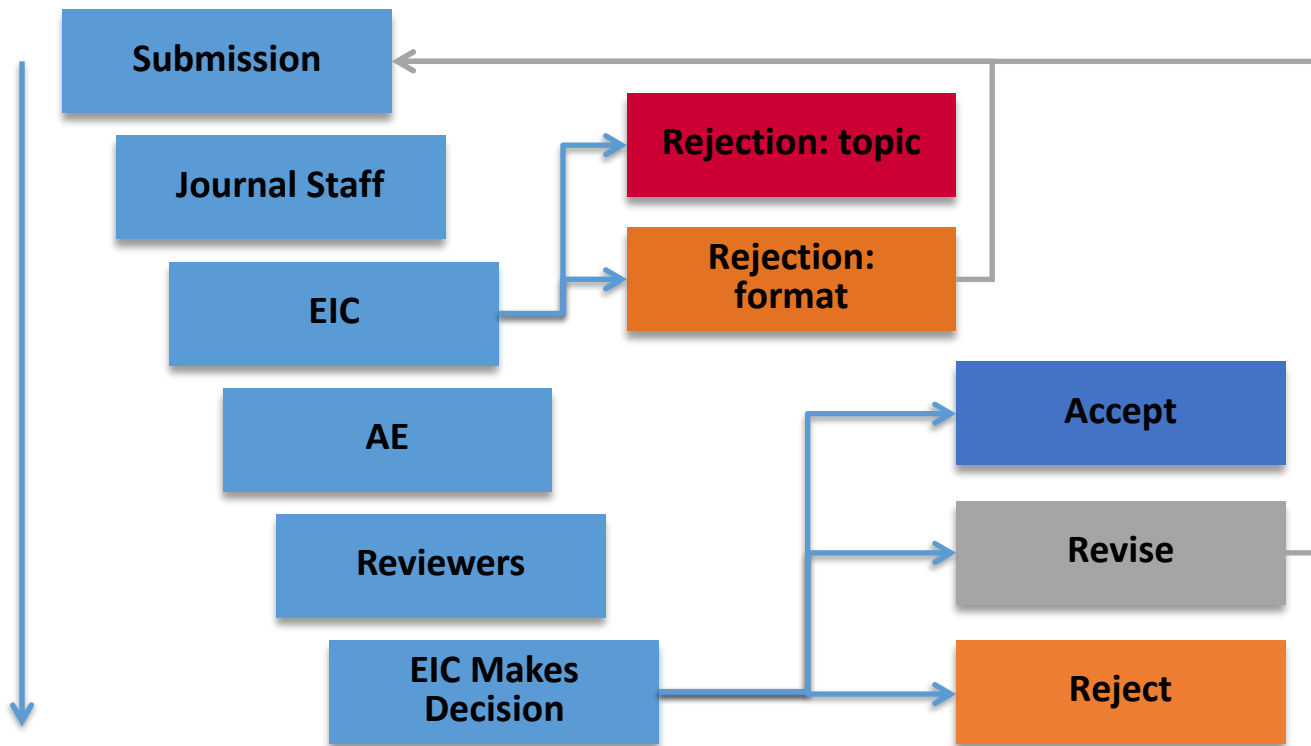
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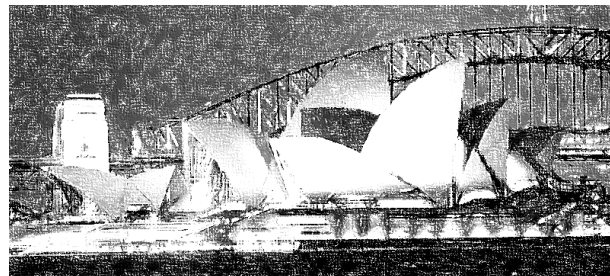
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